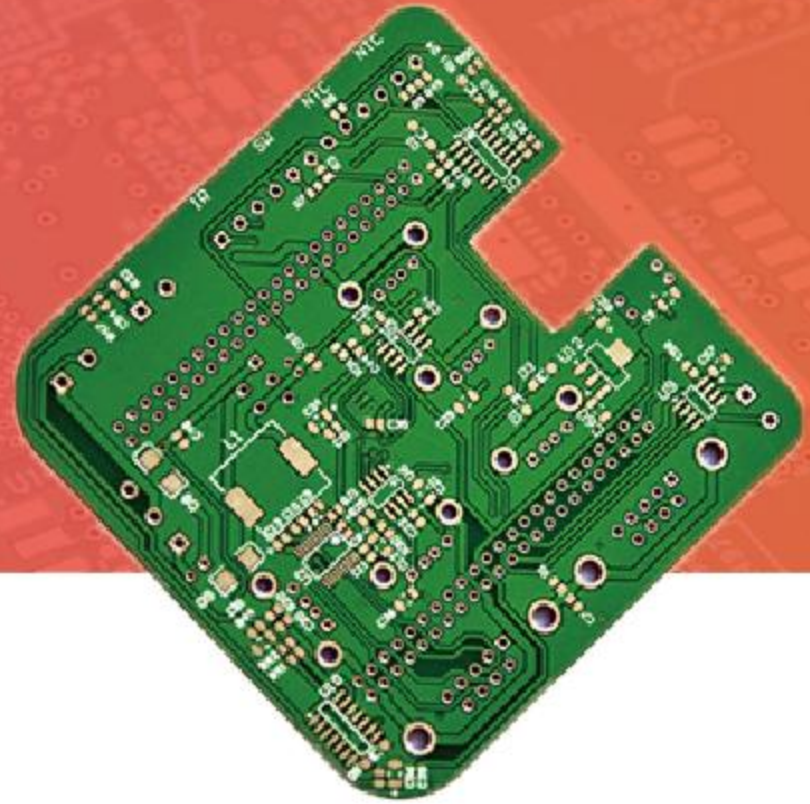


RIGID PCB



CAPABILITIES

Layers	1 - 62L	Min. Line Space	2.5 mil
Max Board Size	24" x 40"	Min. Mechanical Drill/Pad	6 mil 16 mil
Max Board Thickness	.315"	Min. Laser Drill/Pad	4 mil 10 mil
Min. Board Thickness	4L - 16 mil, 6L - 24 mil 8L - 40 mil, 10L - 48 mil 12-16L - 63 mil	PTH Dia. Tolerance	±3 mil
		NPTH Dia. Tolerance	±1 mil
		Hole Position Deviation	±3 mil
HDI Boards	Blind, Buried, Stacked Vias & ELIC	Outline Tolerance	±4 mil
Impedance Control	≤50 OHMS = ±5 OHMS >50 OHMS = ±10%	Solder Mask Dams	2 mil
		Aspect Ratio Laser	1:1
Aspect Ratio Mechanical	Component	Flammability	94V-0
Min. Line Width	Component		

SURFACE FINISHES

- Leaded HASL
- Lead Free HASL
- Immersion Gold (ENIG)
- Immersion Gold (ENEPIG)
- Immersion Silver
- Immersion Tin
- Hard Gold (Fingers)
- Selective Hard Gold
- Wire Bondable Soft Gold
- Flash Gold
- Carbon Ink
- OSP

MATERIALS

- Standard Tg FR-4
- Mid Tg FR-4
- High Tg FR-4
- High Speed Materials
- Mixed Dielectric Constructions
- Halogen Free
- Polyimide

CERTIFICATIONS

- UL
- ISO9001 (Quality System)
- IATF16949 (Automotive)
- ISO13485 (Medical)
- AS9100 (Aerospace)
- ISO14001 (Environmental)
- OHSAS18001 (Safety)
- ISO27001 (IP Protection)

LEAD TIMES

Quick Turn, 5 - 10 Days from
AsiaHigh Mix Low Volume
Medium to High Volume
** Technology level dependent*



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Production Base

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